

REISSUE APPLICATION DECLARATION BY THE INVENTOR	Docket Number (Optional) 1374.34189R00
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I hereby declare that:
 Each inventor's residence, mailing address and citizenship are stated below next to their name.
 I believe the inventors named below to be the original and first inventor(s) of the subject matter which is described and claimed in patent number 5,777,391, granted July 7, 1998 and for which a reissue patent is sought on the invention entitled SEMICONDUCTOR DEVICE HAVING AN IMPROVED CONNECTION ARRANGEMENT BETWEEN A SEMICONDUCTOR PELLET AND BASE SUBSTRATE ELECTRODES AND A METHOD OF MANUFACTURE THEREOF, the specification of which

☐ is attached hereto.

☒ was filed on July 7, 2002 as reissue application number 09/613,541
 and was amended on 04/16/2002; 10/23/2003; 04/17/2005; 07/13/2005; 08/17/2005
 (If applicable) and 11/09/2005

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.
 I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.

☒ I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or (f), or 365(b). Attached is form PTO/SB/02B (or equivalent) listing the foreign applications.

I verily believe the original patent to be wholly or partly inoperative or invalid, for the reasons described below. (Check all boxes that apply.)

☐ by reason of a defective specification or drawing.

☒ by reason of the patentee claiming more or less than he had the right to claim in the patent.

☒ by reason of other errors.

At least one error upon which reissue is based is described below. If the reissue is a broadening reissue, such must be stated with an explanation as to the nature of the broadening:

The original patent claimed less than the Applicants were entitled to claim by failing to claim the subject matter in broadened new claims 26-90. For example, in comparing new claim 26 with the original patent claims 1 and 11, it can be seen that both the original patent claims 1 and 11 used the terminology that "the semiconductor pellet is mounted face down on the rigid substrate." This terminology is not used in new claim 26 since it does not limit the invention to a rigid substrate and does not use the term "face down." Similarly, with regard to original independent claims 14 and 22, these claims define that the resin member seals the semiconductor pellet. Claim 26 defines this differently, specifying that the resin sealing body seals the "main surface of said semiconductor pellet exposed from said slit."

[Page 1 of 2]

This collection of information is required by 37 CFR 1.175. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to take 30 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.

(REISSUE APPLICATION DECLARATION BY THE INVENTOR, page 2)		Docket Number (Optional) 1374.34189X00	
All errors corrected in this reissue application arose without any deceptive intention on the part of the applicant.			
Note: To appoint a power of attorney, use form PTO/SB/81.			
Correspondence Address: Direct all communications about the application to:			
<input checked="" type="checkbox"/> The address associated with Customer Number:		020457	
OR			
<input type="checkbox"/> Firm or Individual Name			
Address			
City	State	Zip	
Country			
Telephone	Email		
<p align="center">WARNING:</p> <p>Petitioner/applicant is cautioned to avoid submitting personal information in documents filed in a patent application that may contribute to identity theft. Personal information such as social security numbers, bank account numbers, or credit card numbers (other than a check or credit card authorization form PTO-2038 submitted for payment purposes) is never required by the USPTO to support a petition or an application. If this type of personal information is included in documents submitted to the USPTO, petitioners/applicants should consider redacting such personal information from the documents before submitting them to the USPTO. Petitioner/applicant is advised that the record of a patent application is available to the public after publication of the application (unless a non-publication request in compliance with 37 CFR 1.213(a) is made in the application) or issuance of a patent. Furthermore, the record from an abandoned application may also be available to the public if the application is referenced in a published application or an issued patent (see 37 CFR 1.14). Checks and credit card authorization forms PTO-2038 submitted for payment purposes are not retained in the application file and therefore are not publicly available.</p> <p>I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine and imprisonment, or both, under 18 U.S.C. 1001, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this declaration is directed.</p>			
Full name of sole or first inventor (given name, family name) Atsushi NAKAMURA			
Inventor's signature <i>Atsushi Nakamura</i>		Date 28 / Jan. / 2008	
Residence Same As Mailing Address		Citizenship Japan	
Mailing Address 3-27-52, Musashidai, Fuchu-shi, Tokyo, Japan			
Full name of second joint inventor (given name, family name) Kunihiko NISHI			
Inventor's signature <i>Kunihiko Nishi</i>		Date 18 / Jan. / 2008	
Residence Same as Mailing Address.		Citizenship Japan	
Mailing Address 2-9-8-1002, Hon-cho, Kokubunji-shi, Tokyo, Japan			
<input type="checkbox"/> Additional joint inventors or legal representative(s) are named on separately numbered sheets forms PTO/SB/02A or 02LR attached hereto.			

DECLARATION – Supplemental Priority Data Sheet

[illegible]

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